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LPDDR3 ATE and System Validation Results:

Listed below are the results from a small sample of LPDDR3 DRAM tested on ATE and Intel(R) reference platforms. Providing this information as a guide to component performance with Intel® reference platforms. This testing is not intended to replace the normal OEM component qualification process. For results on specific Intel® motherboards or OEM production motherboards, please refer to the OEM's list of qualified memory suppliers.

LPDDR3 178ball - 2133/1866 (System Memory Down)								
Supplier	Part Number	Speed	Package Density	Density Die	Package	Width	Die Rev	Date Code
Micron	MT52L256M32D1PF-107 WT:B	1866	8Gb	8Gb	SDP	x32	B	1536
Micron	MT52L512M32D2PF-107 WT:B	1866	16Gb	8Gb	DDP	x32	B	1532
Micron	MT52L1G32D4PG-107 WT:B	1866	32Gb	8Gb	QDP	x32	B	1533
Micron	MT52L256M32D1PF-093 WT:B	2133	8Gb	8Gb	SDP	x32	B	1532
Micron	MT52L512M32D2PF-093 WT:B	2133	16Gb	8Gb	DDP	x32	B	1532
Micron	MT52L1G32D4PG-093 WT:B	2133	32Gb	8Gb	QDP	x32	B	1533
Samsung	K4E8E324EB-EGCG	2133	8Gb	8Gb	SDP	x32	B	1607
Samsung	K4E6E304EB-EGCG	2133	16Gb	8Gb	DDP	x32	B	1607
Samsung	K4EBE304EB-EGCG	2133	32Gb	8Gb	QDP	x32	B	1607
Samsung	K4E6E304EC-EGCF	1866	16Gb	8Gb	DDP	x32	C	1716
Samsung	K4EBE304EC-EGCF	1866	32Gb	8Gb	QDP	x32	C	1716
Samsung	K4E6E304EC-EGCG	2133	16Gb	8Gb	DDP	x32	C	1716
Samsung	K4EBE304EC-EGCG	2133	32Gb	8Gb	QDP	x32	C	1716
Samsung	K4E8E324ED-EGCG	2133	8Gb	8Gb	SDP	x32	D	1849
Samsung	K4E6E304ED-EGCG	2133	16Gb	8Gb	DDP	x32	D	1849
Samsung	K4EBE304ED-EGCG	2133	32Gb	8Gb	QDP	x32	D	1849
SK Hynix	H9CCNNN8GTALAR-NUD	1866	8Gb	8Gb	SDP	x32	A	1623
SK Hynix	H9CCNNNBJTALAR-NUD	1866	16Gb	8Gb	DDP	x32	A	1623
SK Hynix	H9CCNNNCLTALAR-NUD	1866	32Gb	8Gb	QDP	x32	A	1622
SK Hynix	H9CCNNN8GTALAR-NVD	2133	8Gb	8Gb	SDP	x32	A	1630
SK Hynix	H9CCNNNBJTALAR-NVD	2133	16Gb	8Gb	DDP	x32	A	1630
SK Hynix	H9CCNNNCLGALAR-NVD	2133	32Gb	8Gb	QDP	x32	A	1630

LPDDR3 253ball - 1866/2133 (ATE only)								
Supplier	Part Number	Speed	Package Density	Density Die	Package	Width	Die Rev	Date Code
Micron	MT52L256M64D2PP-107 WT:B	1866	16Gb	8Gb	DDP	x64	B	1604
Micron	MT52L512M64D4PQ-107 WT:B	1866	32Gb	8Gb	QDP	x64	B	1602
Micron	MT52L256M64D2PP-093 WT:B	2133	16Gb	8Gb	DDP	x64	B	1642
Micron	MT52L512M64D4PQ-093 WT:B	2133	32Gb	8Gb	QDP	x64	B	1642
Samsung	K3QF3F30BM-AGCG	2133	16Gb	8Gb	DDP	x64	B	1638
Samsung	K3QF4F40BM-AGCG	2133	32Gb	8Gb	QDP	x64	B	1638
SK Hynix	H9CCNNNBKTALBR-NUD	1866	16Gb	8Gb	DDP	x64	A	1639
SK Hynix	H9CCNNNCPTALBR-NUD	1866	32Gb	8Gb	QDP	x64	A	1647

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